

MA2Z367 (MA367)

Silicon epitaxial planar type

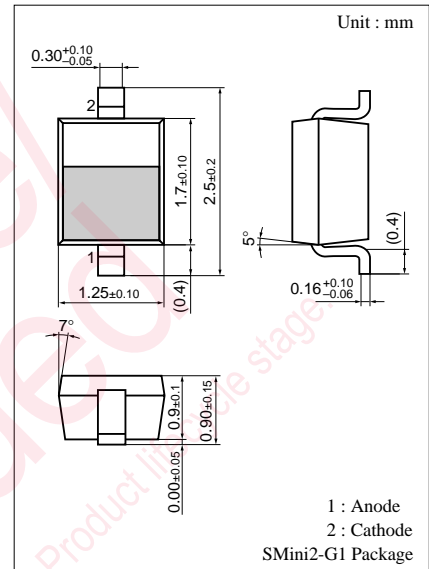
For AFC of UHF and VHF electronic tuner

■ Features

- Large capacitance ratio
- Small series resistance r_D
- S-mini type package, allowing downsizing of equipment and automatic insertion through the taping package

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage (DC)	V_R	30	V
Peak reverse voltage	V_{RM}	34	V
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$



Marking Symbol: 6K

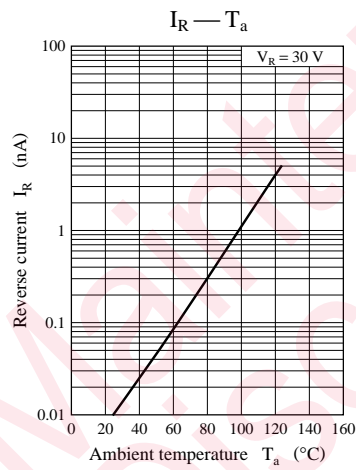
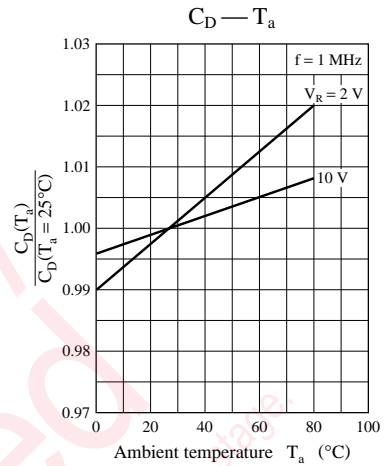
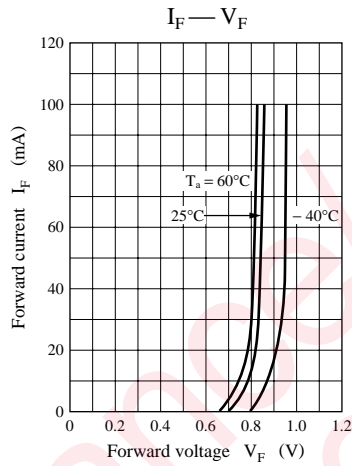
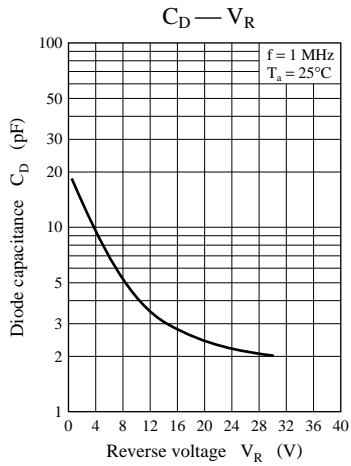
■ Electrical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse current (DC)	I_R	$V_R = 30\text{ V}$			10	nA
Diode capacitance	$C_{D(2V)}$	$V_R = 2\text{ V}, f = 1\text{ MHz}$	10.5		16.0	pF
	$C_{D(10V)}$	$V_R = 10\text{ V}, f = 1\text{ MHz}$	3.3		5.7	pF
Capacitance ratio	$C_{D(2V)}/C_{D(10V)}$		2.8		3.4	—
Series resistance*	r_D	$V_R = 9\text{ pF}, f = 470\text{ MHz}$			1.6	Ω

Note) 1. Rated input/output frequency: 470 MHz

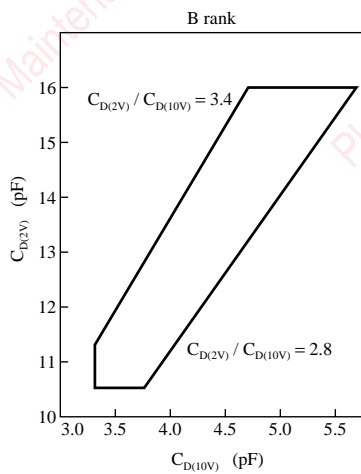
2. * : r_f measuring instrument: YHP MODEL 4191A RF IMPEDANCE ANALYZER

Note) The part number in the parenthesis shows conventional part number.



C_D rank classification

Gap classification table for AFC



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